

**Workshop Challenges on Additive Manufacturing for High Energy Physics**  
**CERN, 5/11/14**

# **Additive Manufacturing for Particle Detectors POLYMERS**

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*PH ALICE Detector & Systems Group*



# Structure of this 30' block

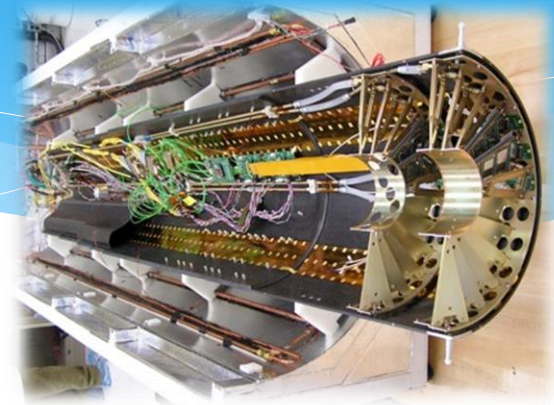
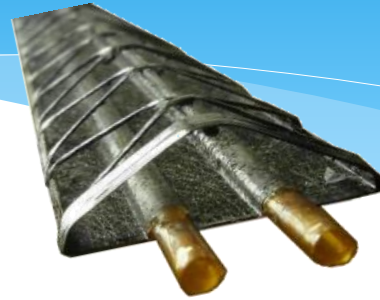
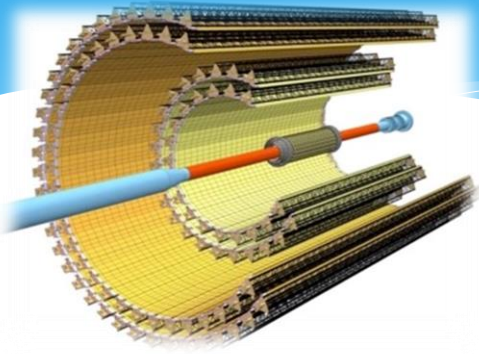
- \* **Rapid Prototyping for High Energy Physics**

- \* High Energy Physics Environment
- \* Range of Machines and Materials at CERN
- \* Use Examples
  - \* Tooling
  - \* Prototypes
  - \* Functional parts

- \* **Challenges for Additive Manufacturing for Detector Technologies**

- \* The Wish List
- \* Breakthrough Technologies for the ALICE Inner Tracker System (ITS)

# LHC Detectors' Environment



- \* Rad hard (several MGray)
- \* Large temperatures range (200°C, 20°C, -25°C, cryo regime)
- \* HV (1 - 30kV)
- \* Massless devices
- \* Material diversity (polymers, C-fiber materials, fiberglass, epoxy, light metals...)
- \* High accuracy (microm)
- \* Large dimensional range (micro to hundreds of meters)
- \* Full project cycles: prototypes to mass production

# Polymer Printers at CERN Polymer lab



**Project 4500  
(Year 2014)**

Accuracy : 0.1mm  
Fast printing  
Low cost  
Multicolor



**SLA® Viper s12 system  
(Year 2013)**

Accuracy 50 microns  
3 resins available  
Fast printing  
Suitable Mechanical, Electrical, Cryogenic and  
Radiation Hardness resistance

# Polymer Printers at CERN

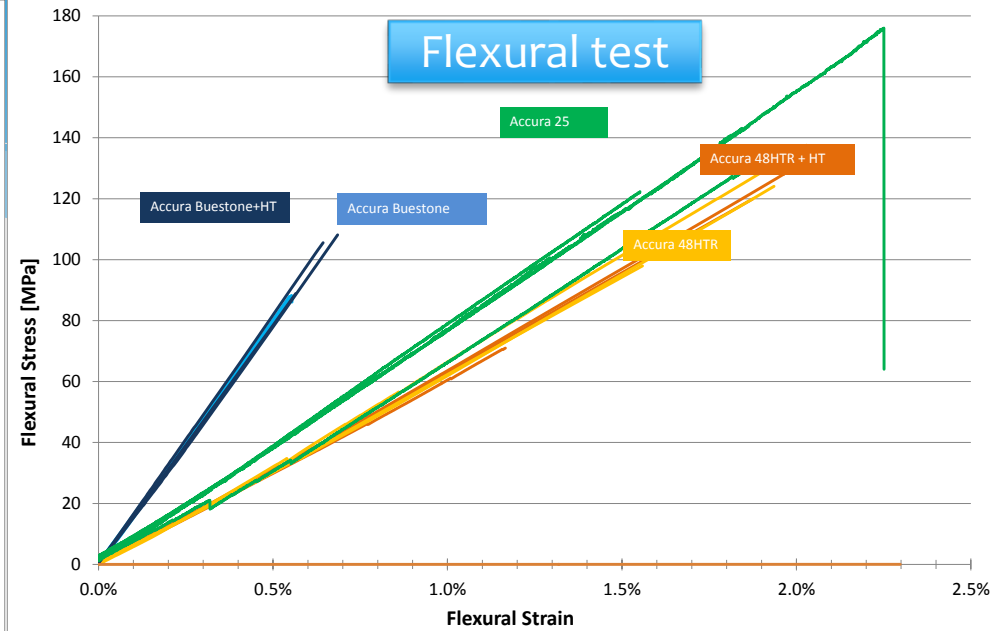
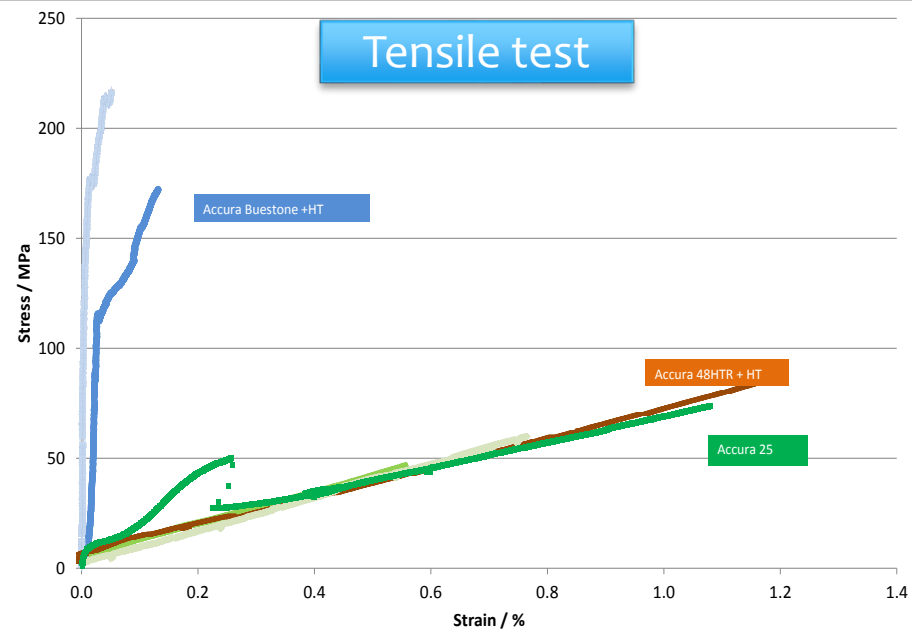
## **3d Dimension Elite** (Fused Deposition Modeling) Used since May 2013, ~ **1200 hours**

- Material: ABS plus, different colors
- Deposition of soluble support
- Maxi part dimension: 203 x 203 x 305
- Layer thickness (Z movement): 0.178 or 0.254mm
- Solid part or «light» (massive external wall + structure like honey comb)
- Estimated accuracy: ~ +/- 0.1mm
- Mini thickness wall: 0.6mm



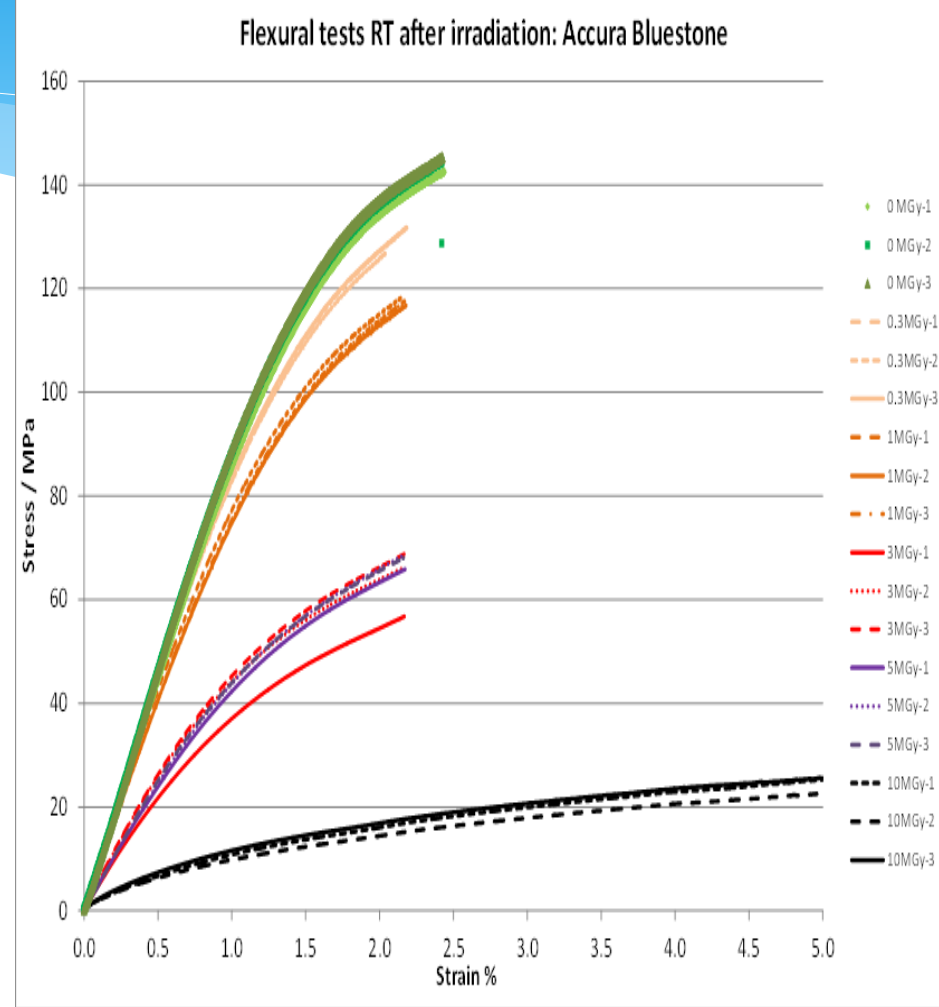
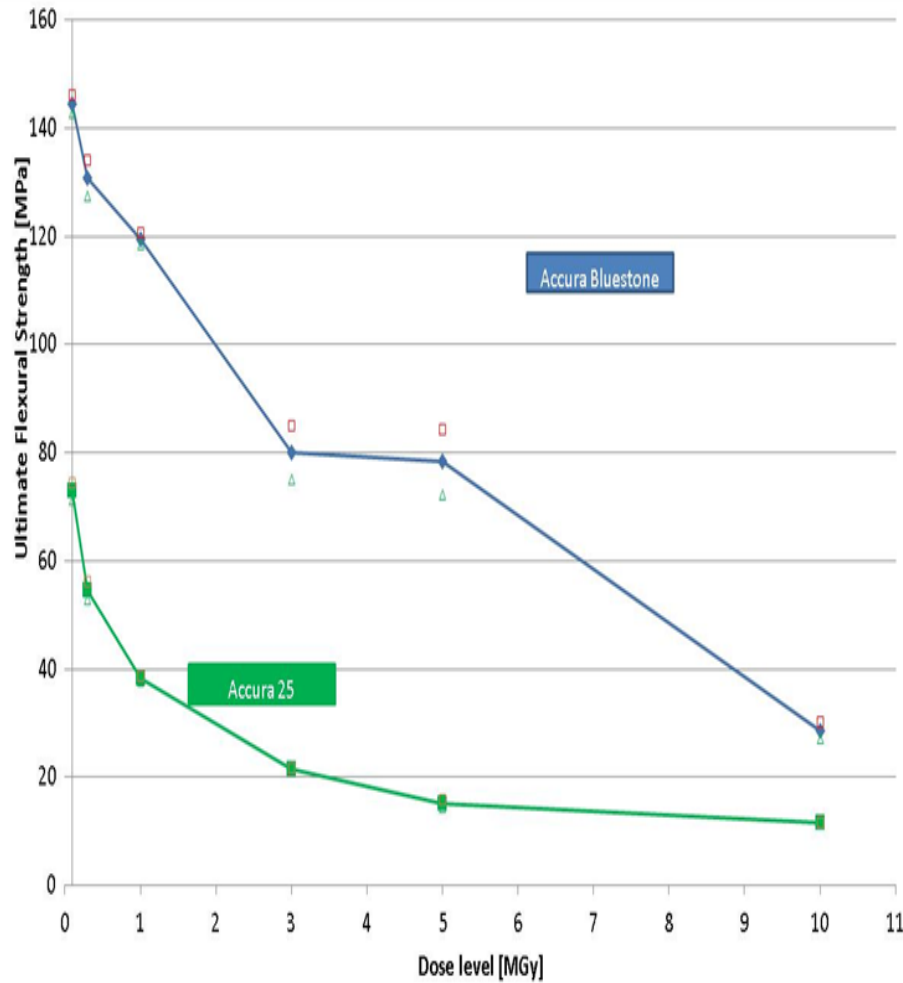
# Mechanical test Properties 77K

TE-MSC



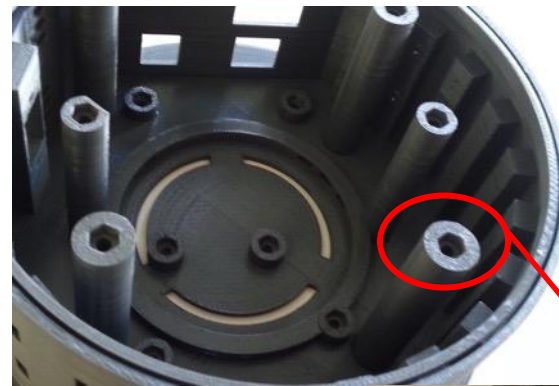
|                                  | Accura 25 | Accura 48HTR | Accura 48HTR +HT | Accura Bluestone | Accura Bluestone +HT |
|----------------------------------|-----------|--------------|------------------|------------------|----------------------|
| Ultimate tensile strength [MPa]  | 70±8      | NA           | 85               | NA               | 190±25               |
| Fracture tensile strain [%]      | 0.9±0.3   | NA           | 1.2              | NA               | 0.07±0.02            |
| Ultimate flexural strength [MPa] | 145±27    | 115±20       | 127±7            | 87±1             | 105±3                |
| Fracture flexural strain [%]     | 1.9±0.35  | 1.8±0.2      | 2±0.1            | 0.53±0.03        | 0.8±0.03             |
| Tensile E modulus [MPa]          | 8000±650  | NA           | 7500±300         | NA               | 15600±300            |

# Radiation resistance materials test

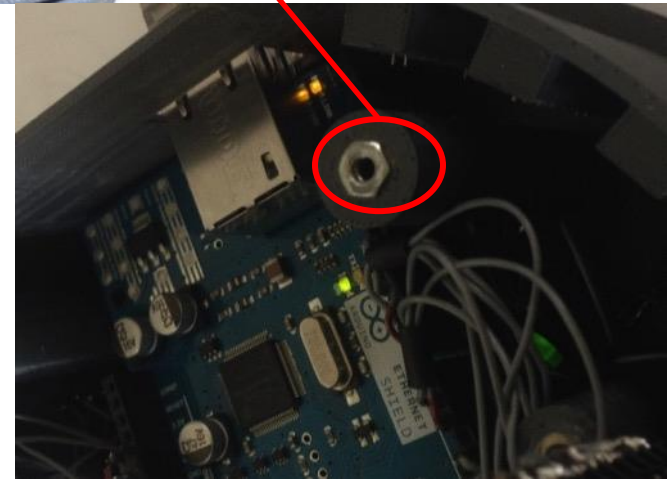


# Research on Production Techniques

Threaded holes, holes machined,  
inserts...



Gluing: use of  
cyanoacrylate

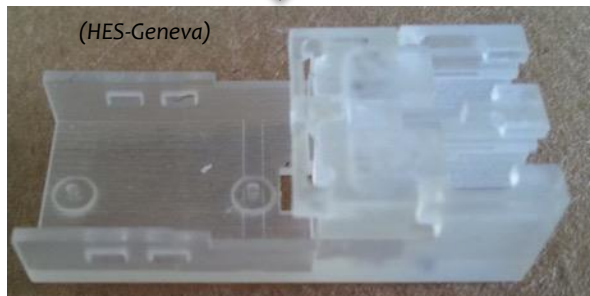
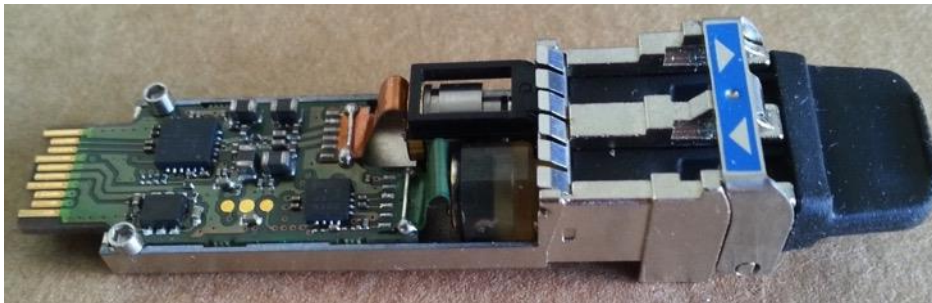




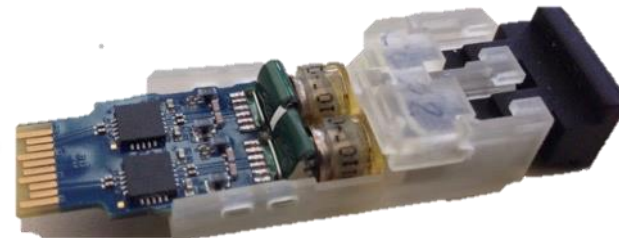
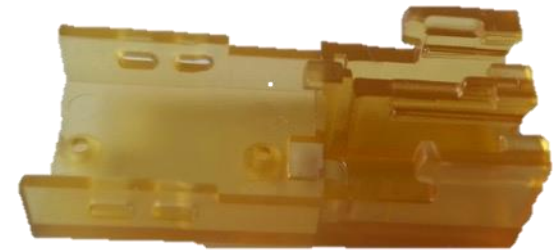
# Use Examples Opto-link Latch

Goal: Replacement of commercial metallic latch by low-mass ultem latch  
RP for **quick validation** of dimensional tolerances for final moulding process

Original Metallic latch



Final Ultem latch

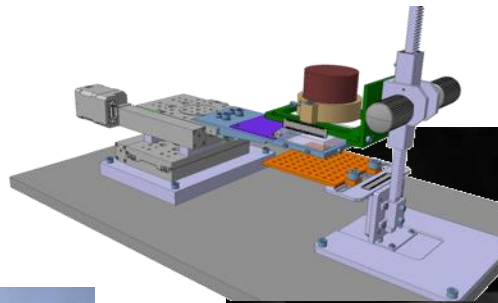
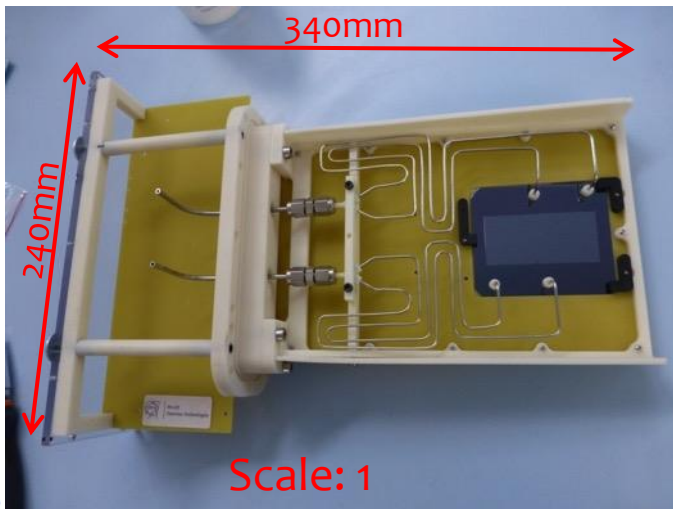


# Use Examples: Tooling, Supports, Test fixtures

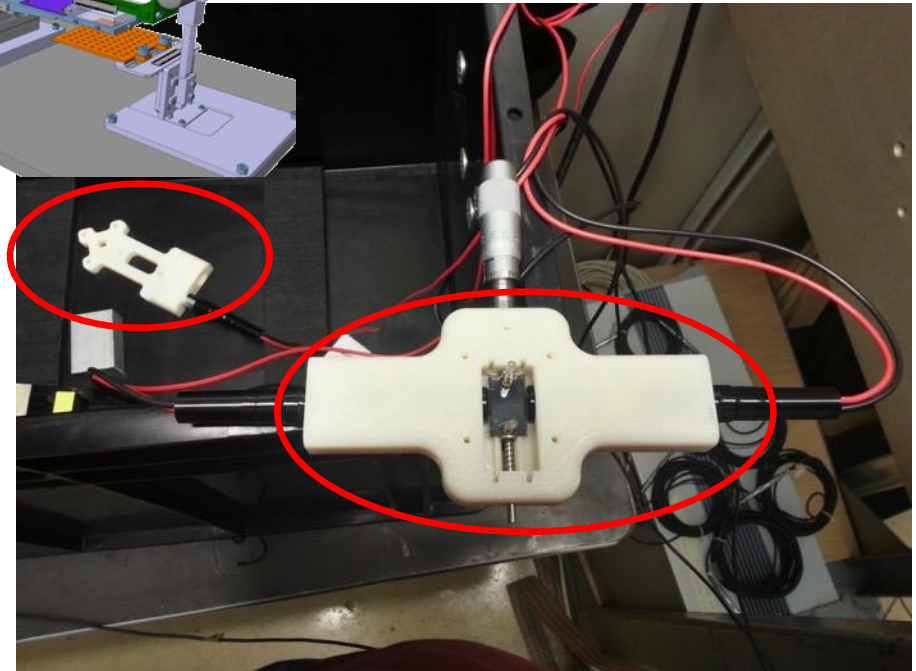
Achieved: Quick and cheap production of parts to enable tests of detectors assemblies and detector services and thus provide rapid feedback for final designs

## NA62 GTK Module

Sensor + microfluidic cooling plate + pipes + support



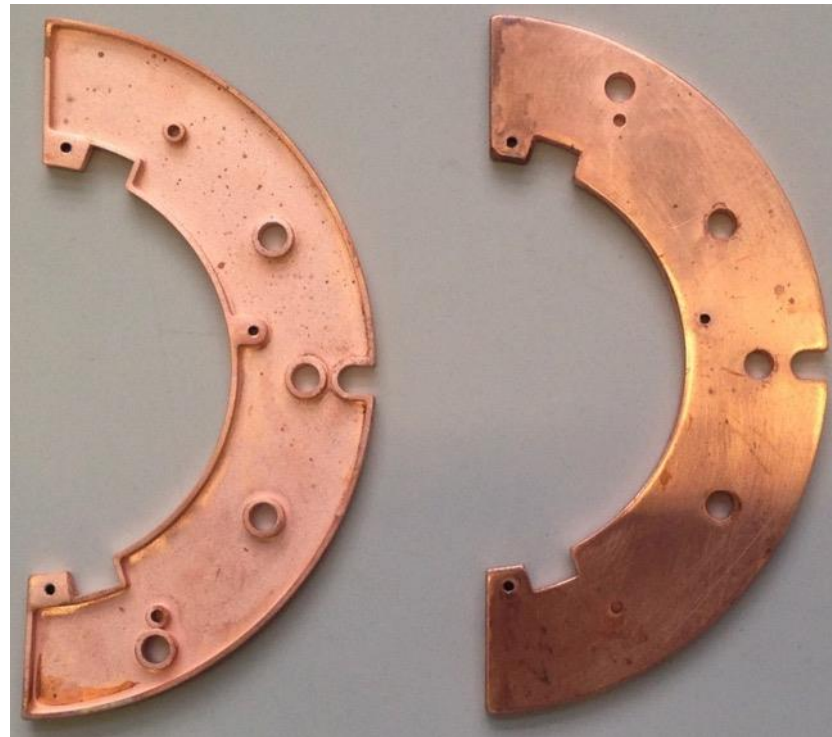
## Microfluidic Scintillating detector



# Use Examples: Functional Parts

## PCB support covered by 10 $\mu$ m copper layer

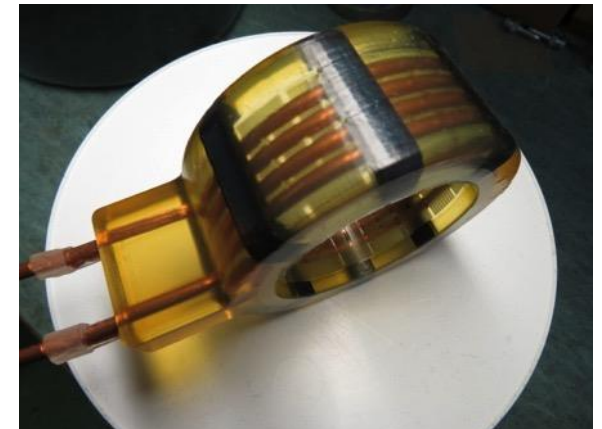
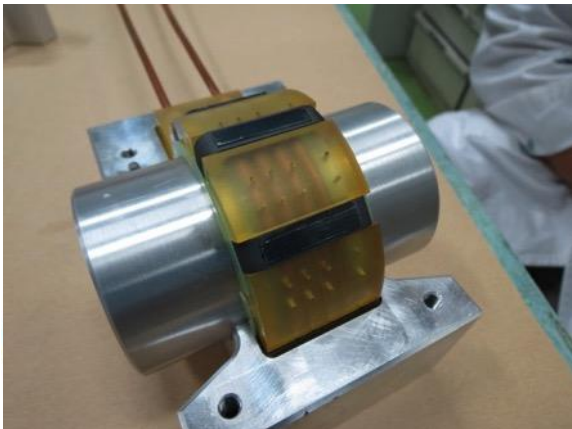
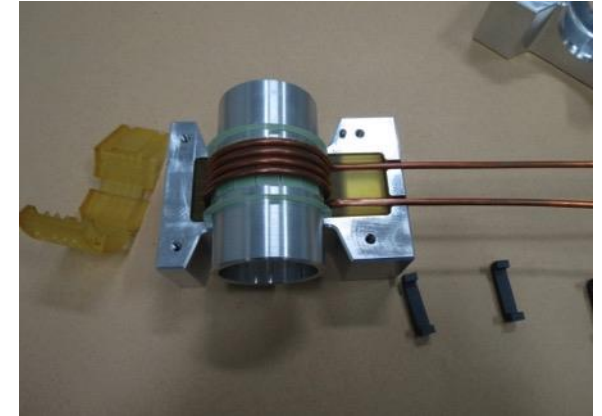
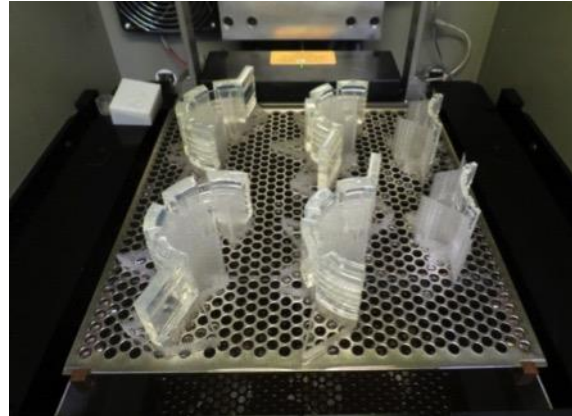
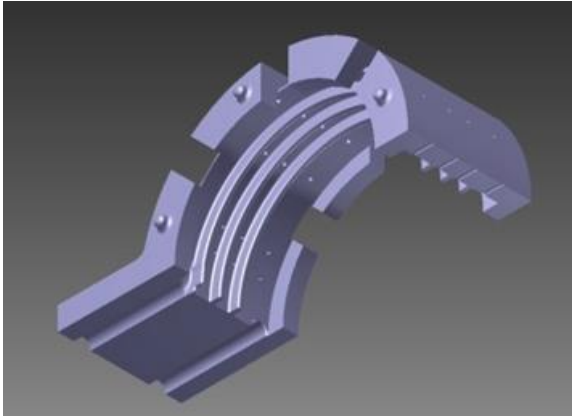
*Resin Accura Bluestone (resin with ceramic filler) because of radhard environment. Copper deposition is a first.*



# Use Examples: Functional Parts

## RF Antenna For LINAC4 Ion Source

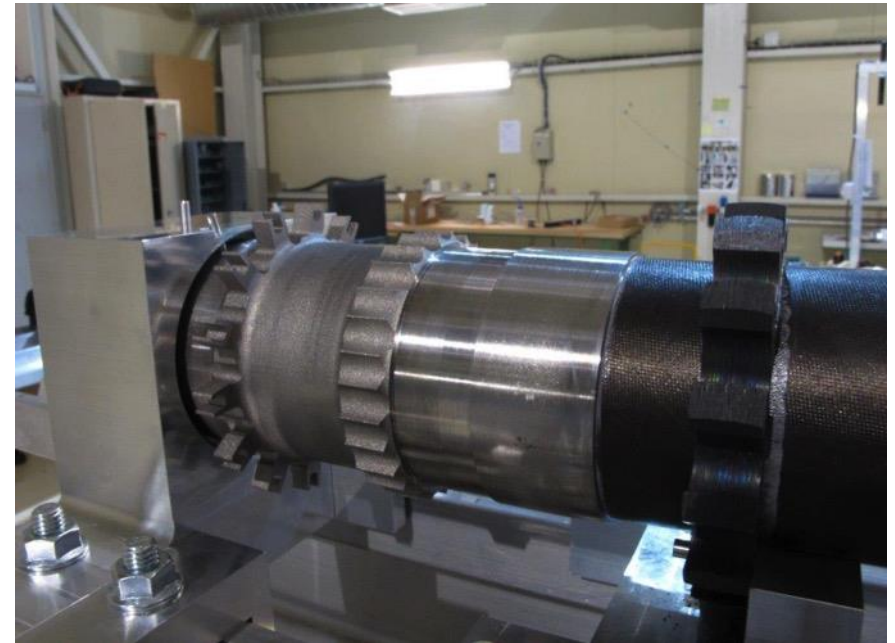
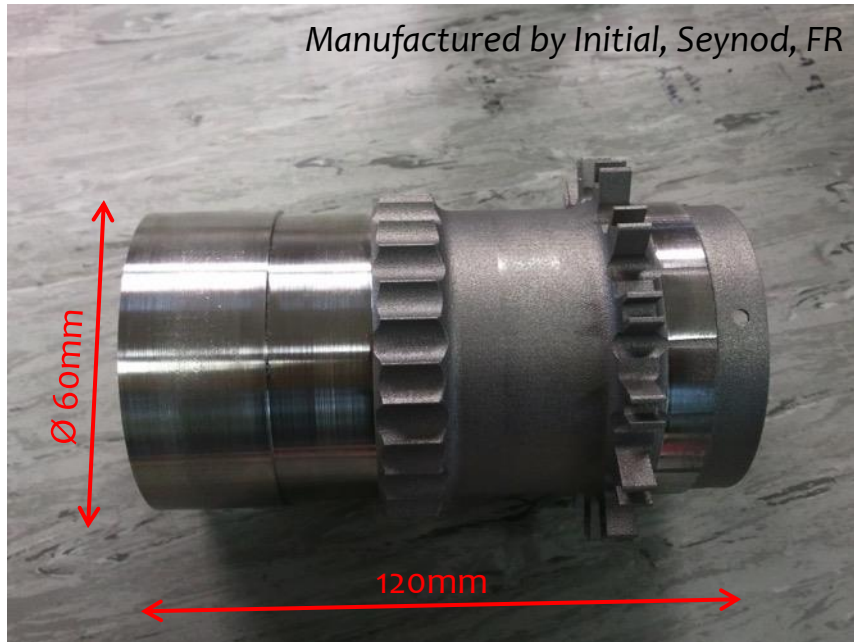
2 Supports made in 3D epoxy resin to replace 11 components previously machined in G11, Assembly, Epoxy vacuum impregnation, and demoulding  
**Achieved: gain in time, cost, assembly simplicity, and final performance**



# Use Examples: Functional Parts

Titanium extremity of Atlas IPT, glued on a carbon fibre pipe

*Achieved: Complex shape piece impossible to obtain by std manufacturing process  
(Only 4 parts manufactured. Internal diameter partially machined after DMLS process)*

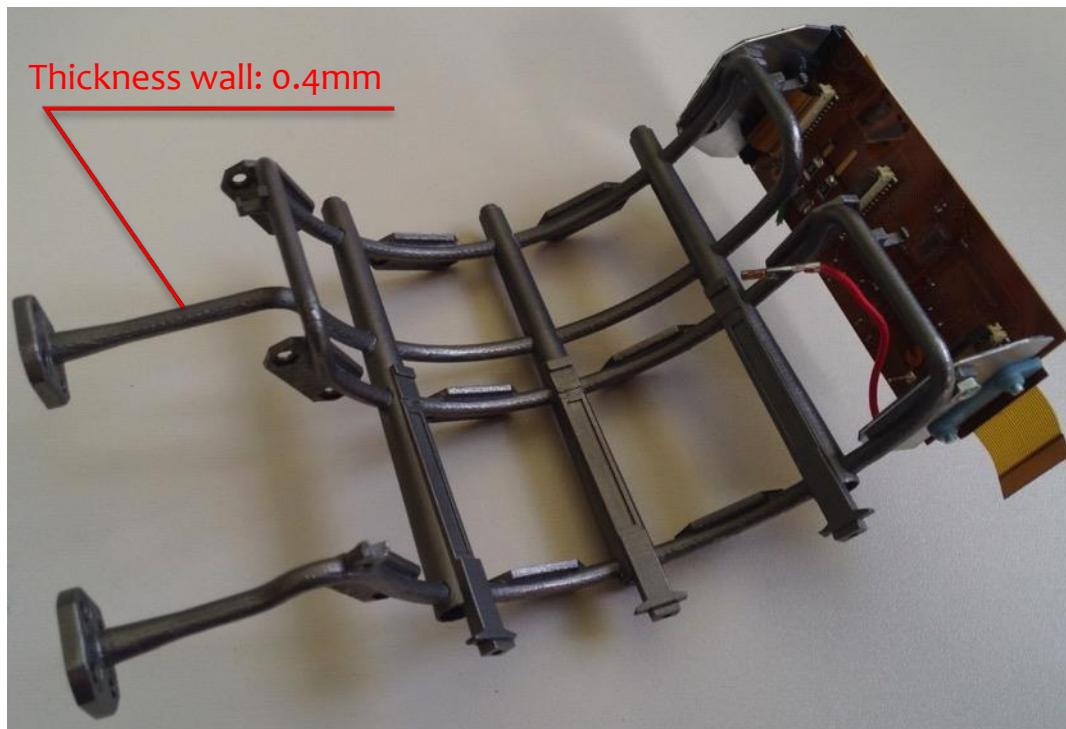


# Use Examples: Functional Parts

## Cooling pipes and support structure

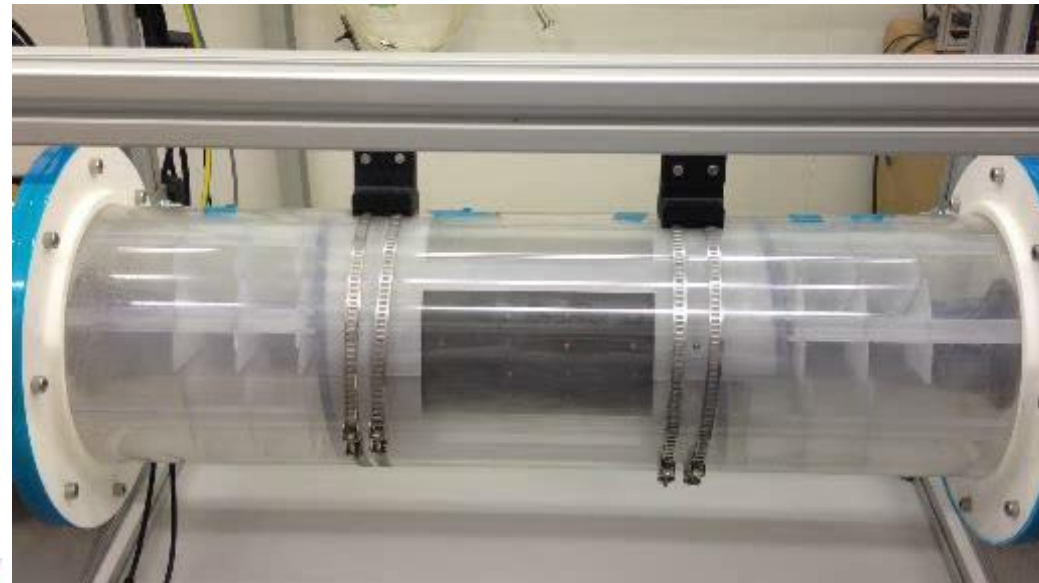
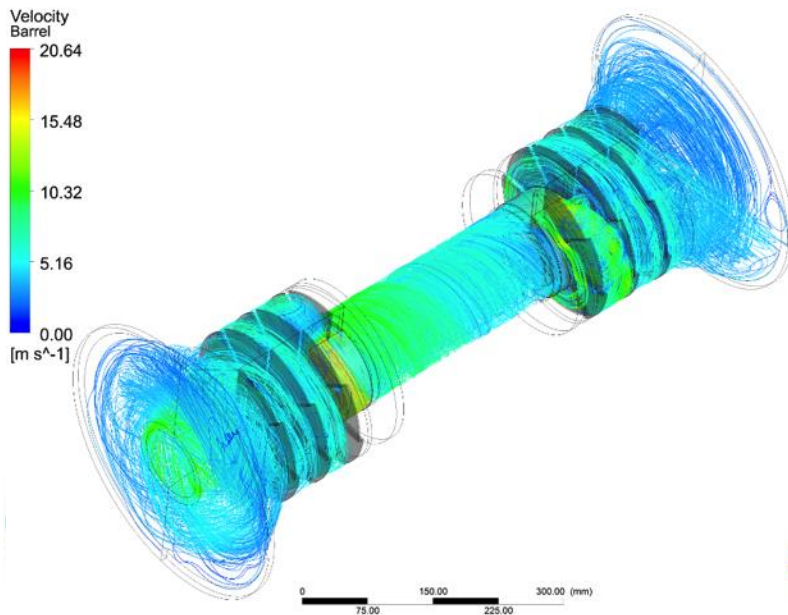
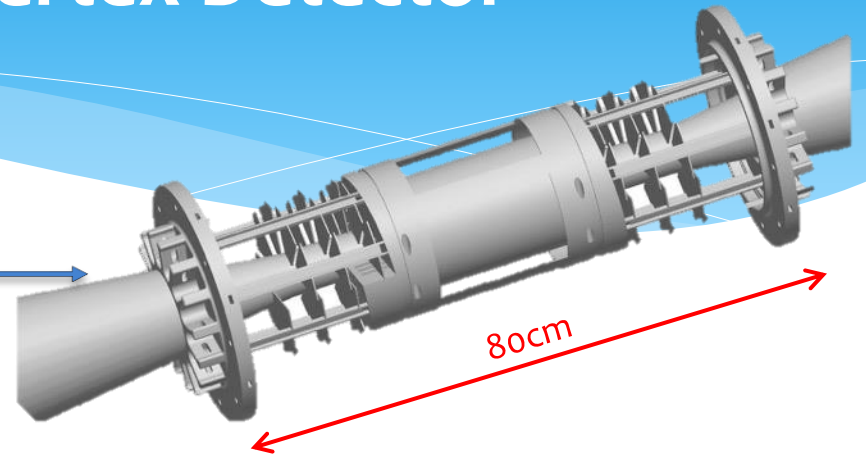
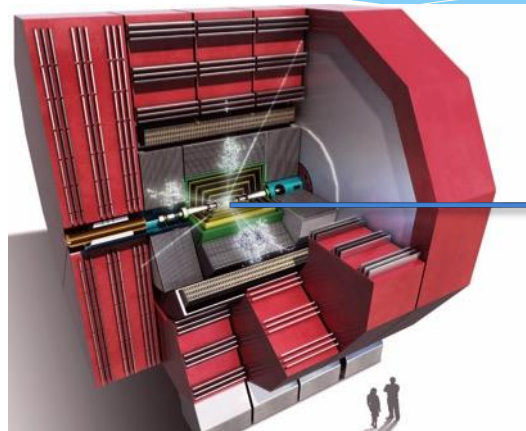
Titanium module support made by SLM process. To improve cooling performance, and decrease pressure drop, a special finishing process (SILC) was applied inside the pipes (made by LayerWise)

**Several functionalities included in 1 structure:** electronic cards support, complex cooling pipes with inlet and outlet connections, tested at 15 bar

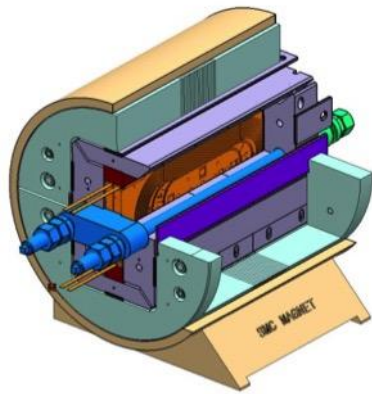


# Use Examples: 1 to 1 Mockups

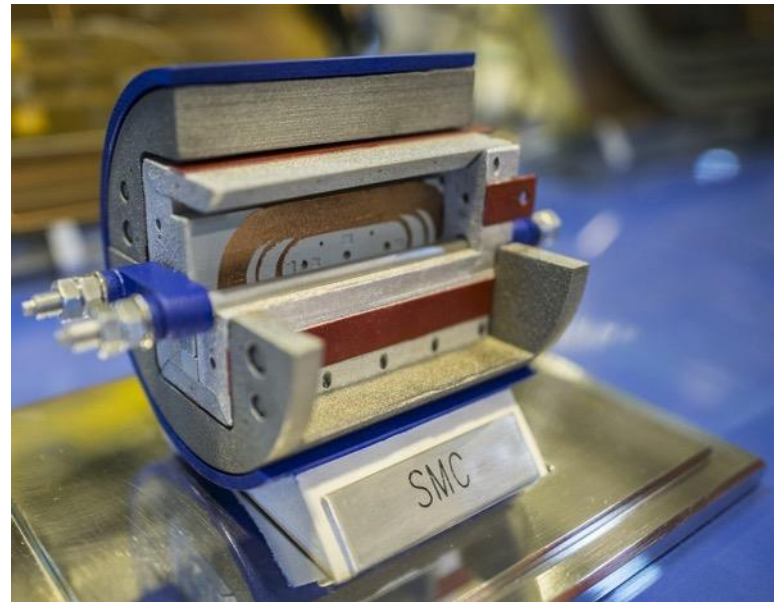
## Linear Collider Vertex Detector



# Use Examples: Models



Magnet prototype  
Short Model Coil (SMC)  
25% reduction scale  
120mm x130mm

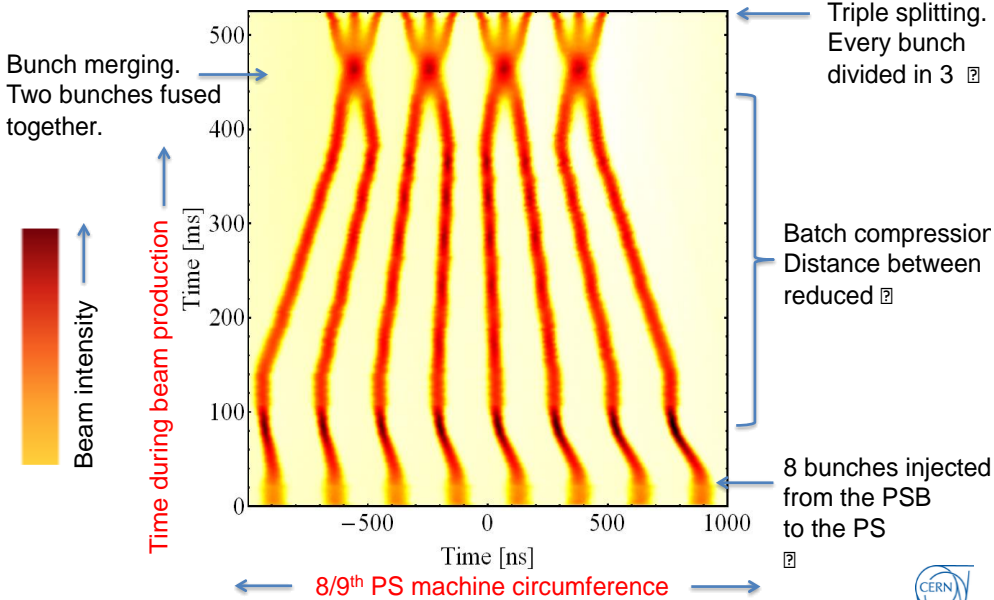




# Use Examples: Dreams

3D Model of RF gymnastics for LHC-beam production (BCMS scheme in PS)

## BCMS full RF gymnastics



# The Obvious Advantages

- \* Economical and quick production of parts and tools
- \* Reduction of assembly steps
- \* Reduce waste (economy for raw materials)
- \* Quick feedback at design and proto phases (less design flaws)
- \* Increased visualization capabilities
- \* Manage impossible geometries
- \* Produce multifunctional devices: reducing mass, space...
- \* ...

# The Wish List

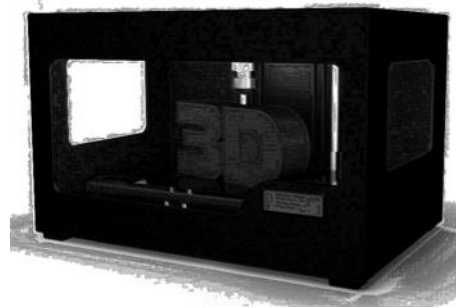
From present 3D-aided design ...

... to future 3D Manufacturing

Modelling

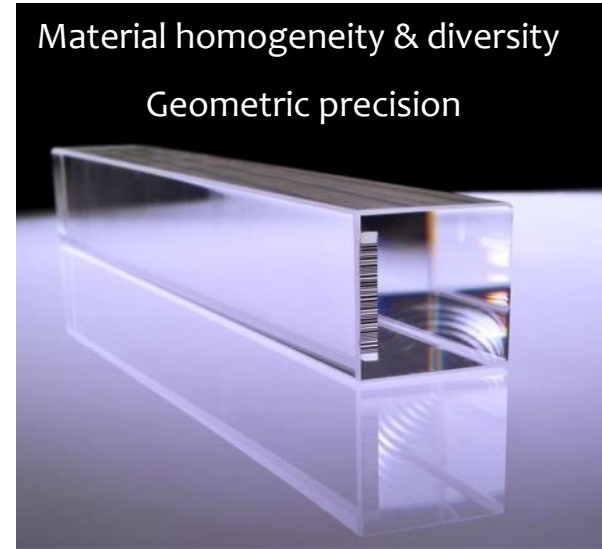


Prototyping



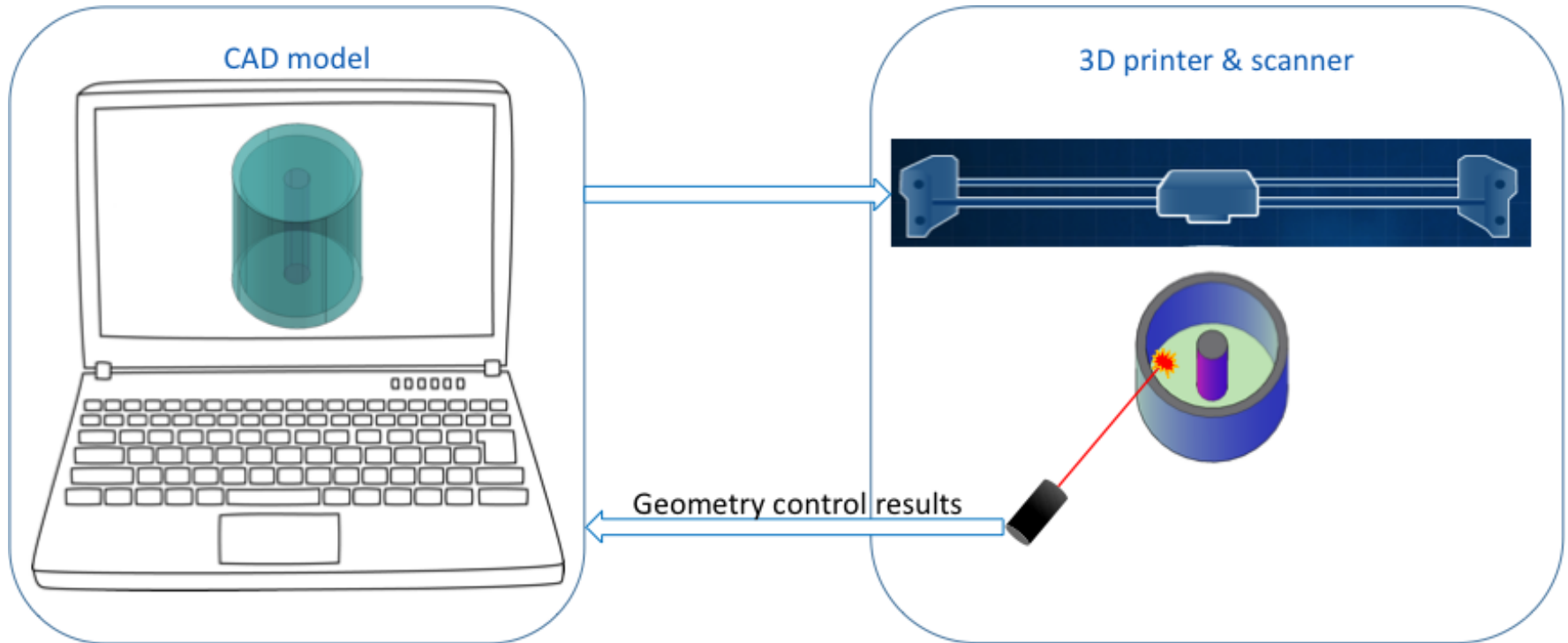
Physical creation brings a new dimension to the design process

Material homogeneity & diversity  
Geometric precision



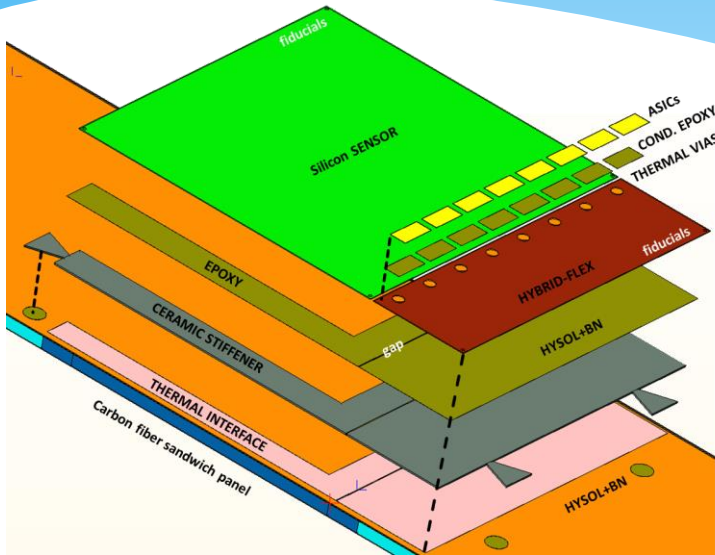
# The Wish List

## Integrated design, manufacturing & QA

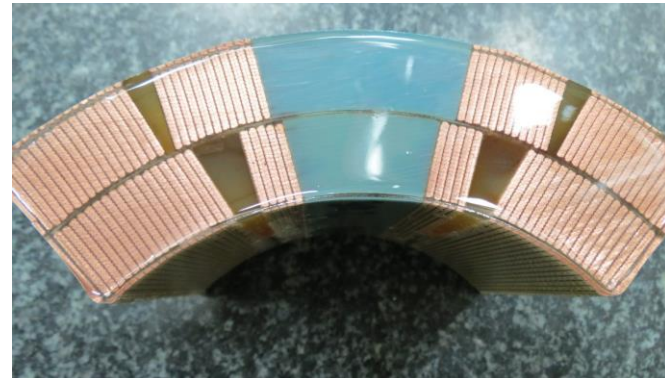
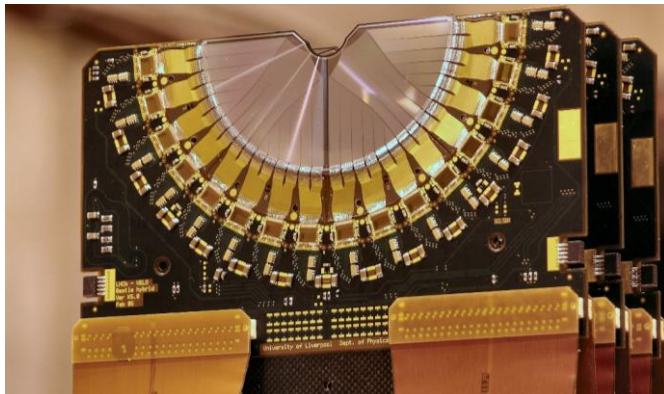


# The Wish List

## Multi-Materials for Manufacturing



Cutting view of a coil: cable in copper winding around head spacer in insulating materials (epoxy). The assembly is impregnated by liquid epoxy on vacuum and curing.



# Silicon Trackers at LHC

Catalog of today's technologies for a particle detector (operational in 2018), and basis for reflection about how/if these technologies and production/assembly technologies could evolve for future tracker systems

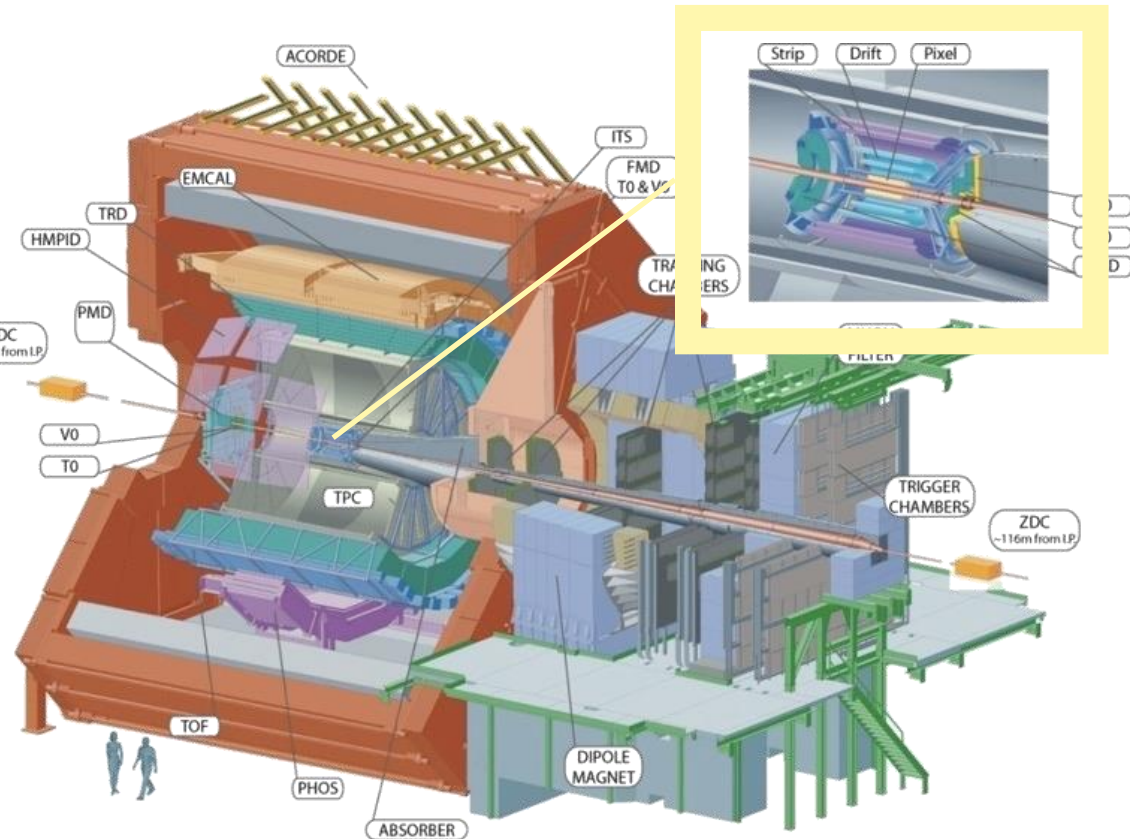
- \* Silicon tracking detectors are used in all LHC experiments
- \* **Upgrades of the present tracker systems, which will have to meet more stringent requirements**, are planned for the LHC shutdown periods 2018 and 2023
- \* Project R&D and production time is typically in the range of several years → **upgrades for 2018 present today's state of the art technologies**
- \* **Upgrades planned for 2023 will strongly profit from new developments starting now**
- \* **Example presented: ALICE ITS Upgrade (2018)**

| Upgrades     | ~Area               |      |
|--------------|---------------------|------|
| ALICE ITS    | 10.3 m <sup>2</sup> | 2018 |
| ATLAS Pixel  | 8.2 m <sup>2</sup>  | 2023 |
| ATLAS Strips | 193 m <sup>2</sup>  | 2023 |
| CMS Pixel    | 4.6 m <sup>2</sup>  | 2023 |
| CMS Strips   | 218 m <sup>2</sup>  | 2023 |
| LHCb VELO    | 0.15 m <sup>2</sup> | 2018 |
| LHCb UT      | 5 m <sup>2</sup>    | 2018 |

# ALICE Experiment

## Inner Tracking System Upgrade

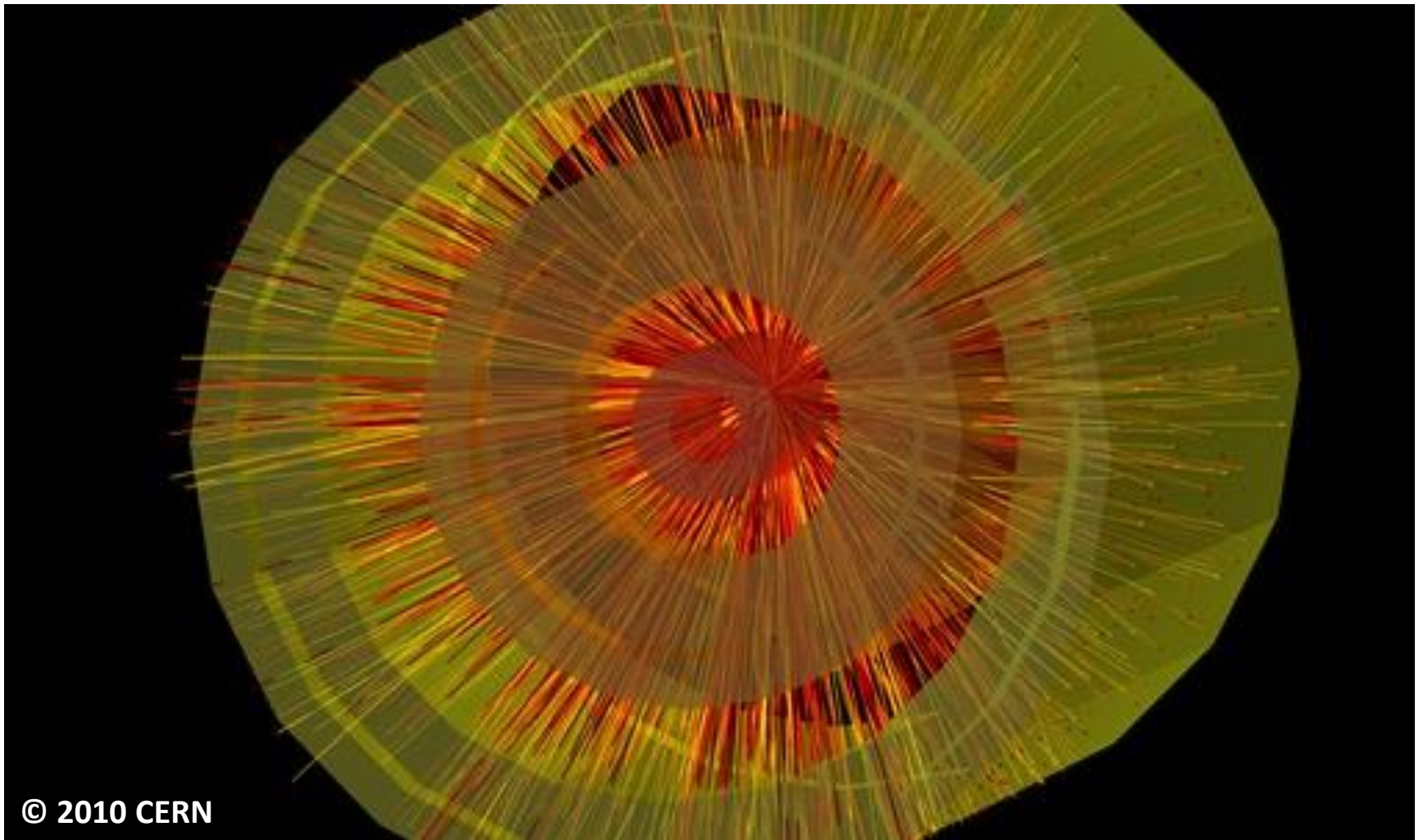
- **ALICE** is an experiment at the LHC dedicated to study heavy ion collisions.
- At the center of the experiment, closest to the interaction point, is the **Inner Tracking System (ITS)**.
- The ITS is based on **silicon tracking detectors**, using presently three different technologies.
- In 2018/19 the entire ITS (~10 m<sup>2</sup>) will be replaced with CMOS monolithic silicon pixel detectors.



**Size: 16 m high, 26 m long**  
**Weight: 10,000 tons**

**Collaboration:**  
1200 members  
131 institutes  
36 countries

Operation of silicon tracking detectors in dense particle track environment:



© 2010 CERN

Events recorded by the ALICE experiment from the first lead ion collisions, at a centre-of-mass energy of 2.76 TeV per nucleon pair.

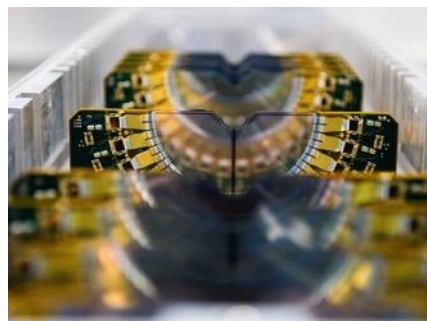


# Silicon Tracking Detectors

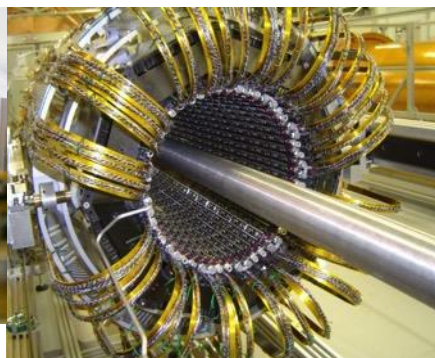
- Complex systems operated in a challenging high track density environment
- **Stringent requirements on radiation hardness, cooling, material budget, etc.**
- Innermost regions usually equipped with pixel detectors



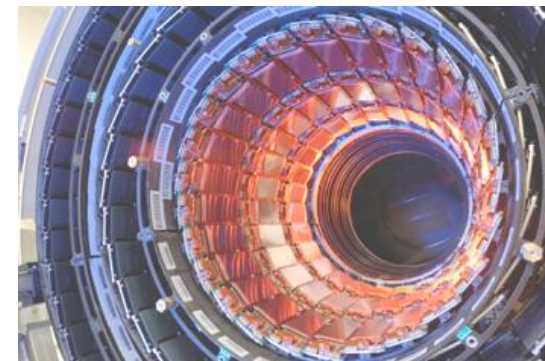
ALICE Pixel Detector



LHCb VELO



ATLAS Pixel Detector



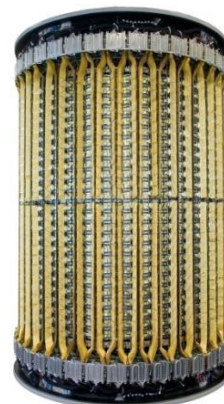
CMS Strip Tracker IB



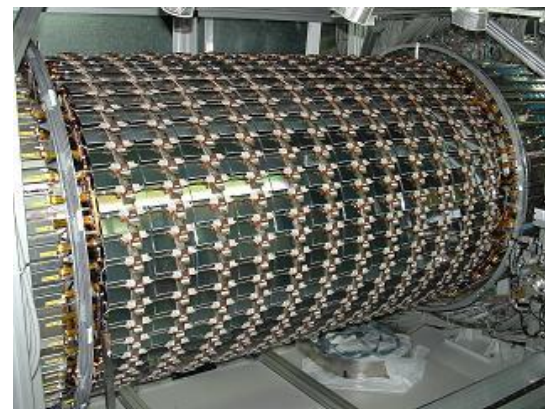
CMS Pixel Detector



ALICE Drift Detector



ALICE Strip Detector

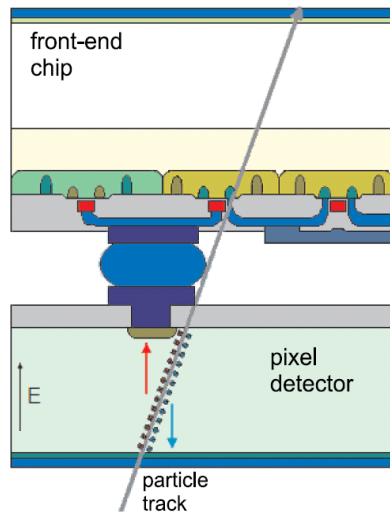


ATLAS SCT Barrel

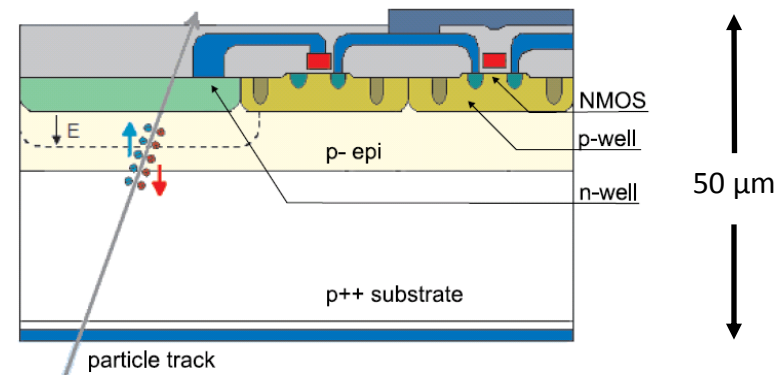
# Hybrid and Monolithic Silicon Pixel Detectors

- Present LHC experiments are using **hybrid pixel detectors**, composed of a silicon sensor connected to a front-end chip.
- The **ALICE ITS upgrade** will use **monolithic silicon pixel detectors**, which will include the sensing part inside the electronic chip --> **50  $\mu\text{m}$  thin silicon chip**

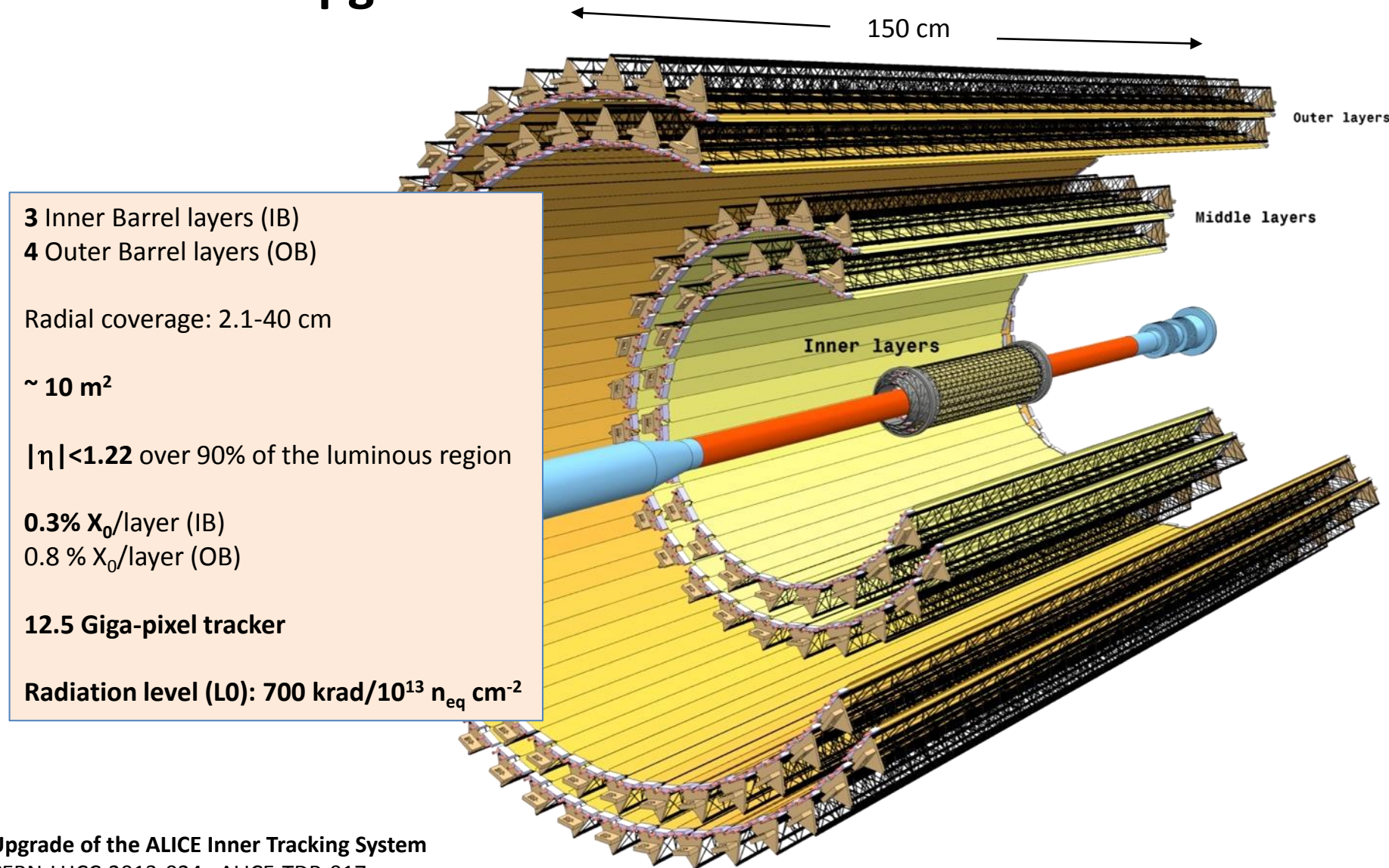
## Hybrid Pixel Detector



## Monolithic Pixel Detector (example)



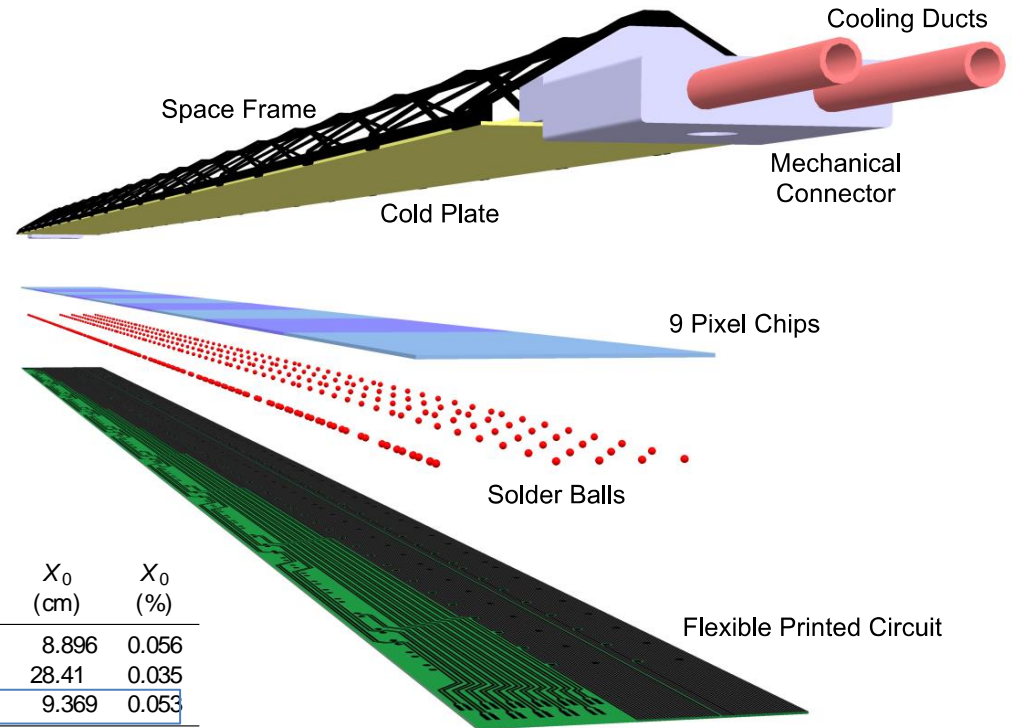
# ALICE ITS Upgrade



# ALICE ITS Upgrade: Inner Layer Stave

Light weight, compact modules to minimize material budget:

- 50  $\mu\text{m}$  silicon sensors connected via solder points to a 2-layer Al(Cu)-polyimide flex cable
- Mechanical support and cooling
- Power and signal connections to each chip

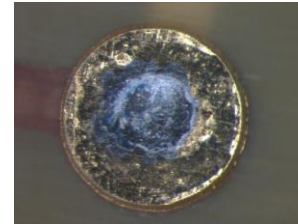
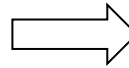
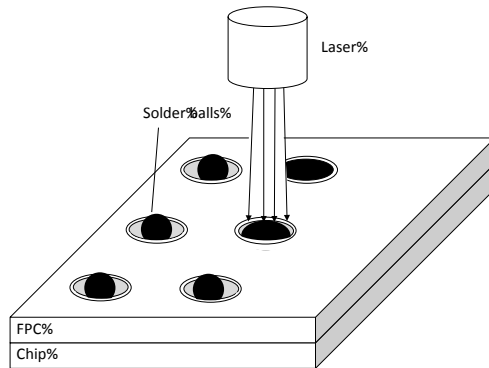


Inner barrel stave  
ALICE ITS TDR

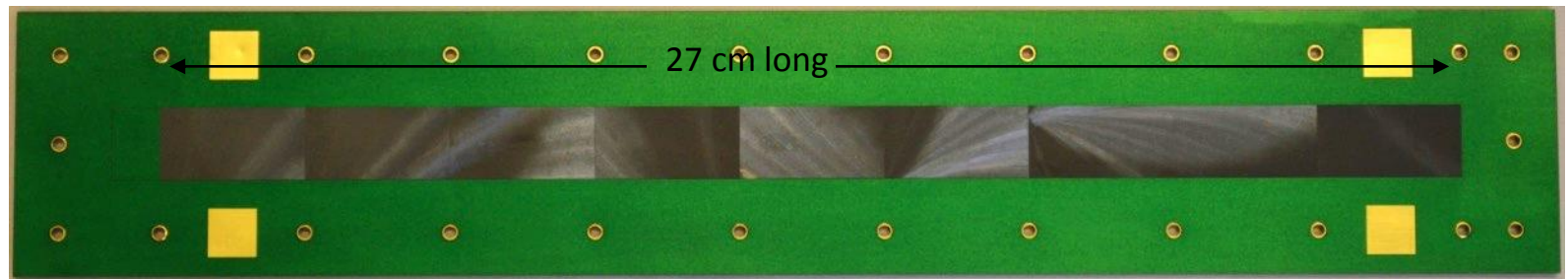
| Stave element | Component             | Material      | Thickness ( $\mu\text{m}$ ) | $X_0$ (cm) | $X_0$ (%) |
|---------------|-----------------------|---------------|-----------------------------|------------|-----------|
| HIC           | FPC Metal layers      | Aluminium     | 50                          | 8.896      | 0.056     |
|               | FPC Insulating layers | Polyimide     | 100                         | 28.41      | 0.035     |
|               | Pixel Chip            | Silicon       | 50                          | 9.369      | 0.053     |
| Cold Plate    |                       | Carbon fleece | 40                          | 106.80     | 0.004     |
|               |                       | Carbon paper  | 30                          | 26.56      | 0.011     |
|               | Cooling tube wall     | Polyimide     | 25                          | 28.41      | 0.003     |
|               | Cooling fluid         | Water         |                             | 35.76      | 0.032     |
|               | Carbon plate          | Carbon fibre  | 70                          | 26.08      | 0.027     |
|               | Glue                  | Eccobond 45   | 100                         | 44.37      | 0.023     |
| Space Frame   |                       | Carbon rowing |                             |            | 0.018     |
| Total         |                       |               |                             |            | 0.262     |

# Example: ALICE ITS Inner Layer Stave

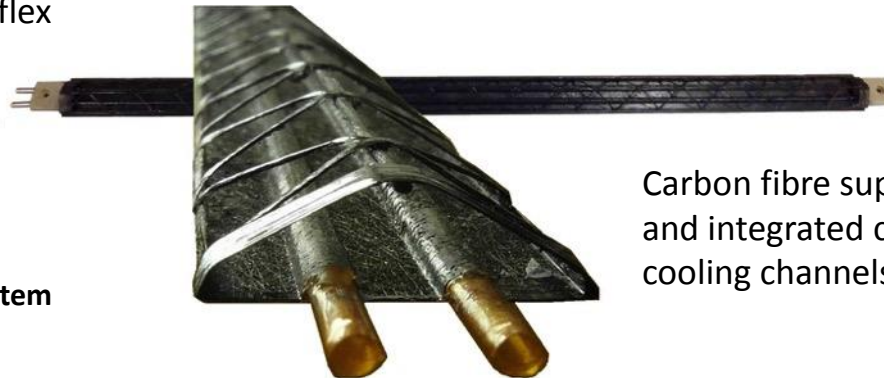
**Sandwich structure:** Silicon + flex cable and interconnection + cooling plate + mechanical support



Direct on chip laser soldering

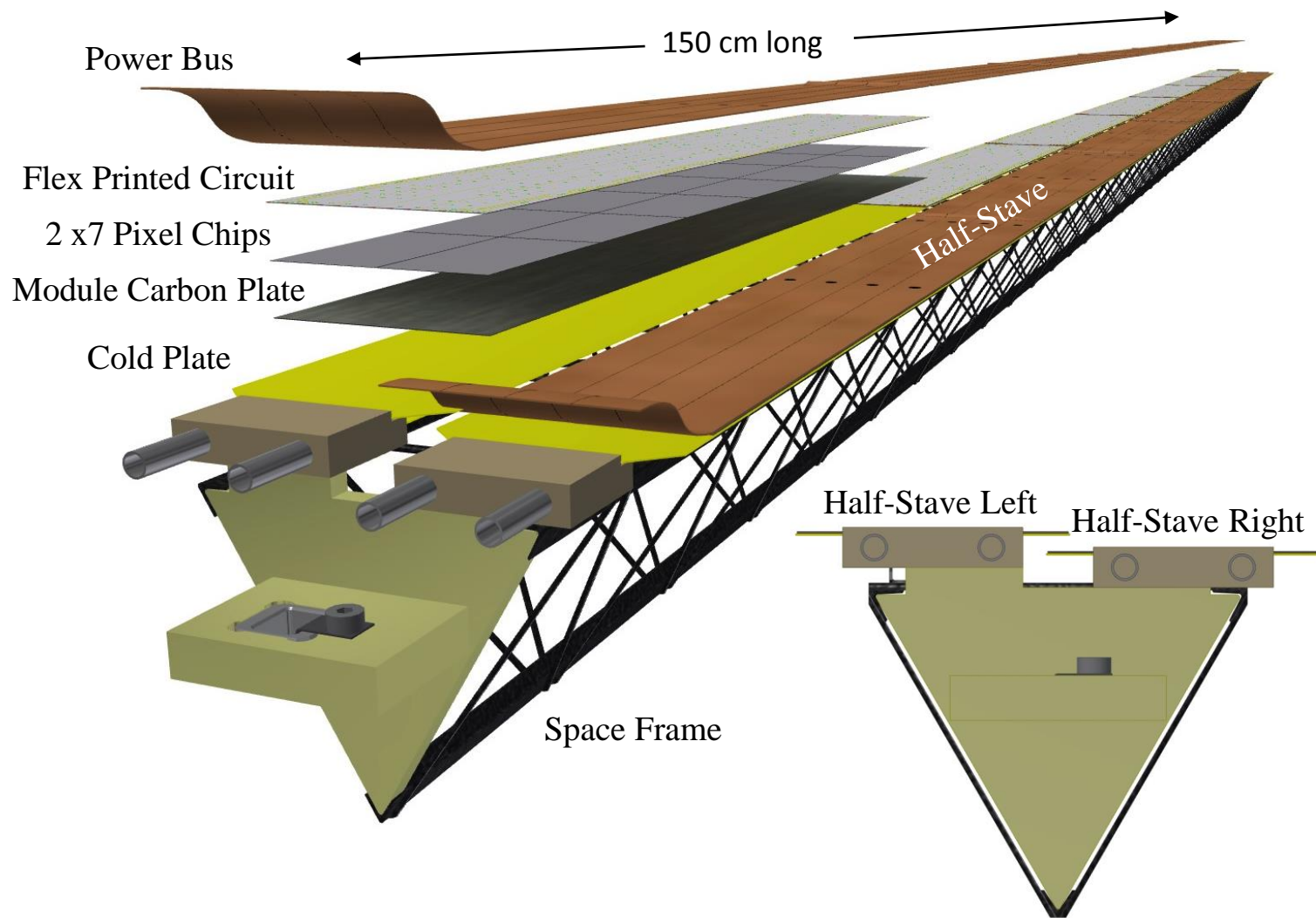


50  $\mu$ m chips soldered to flex



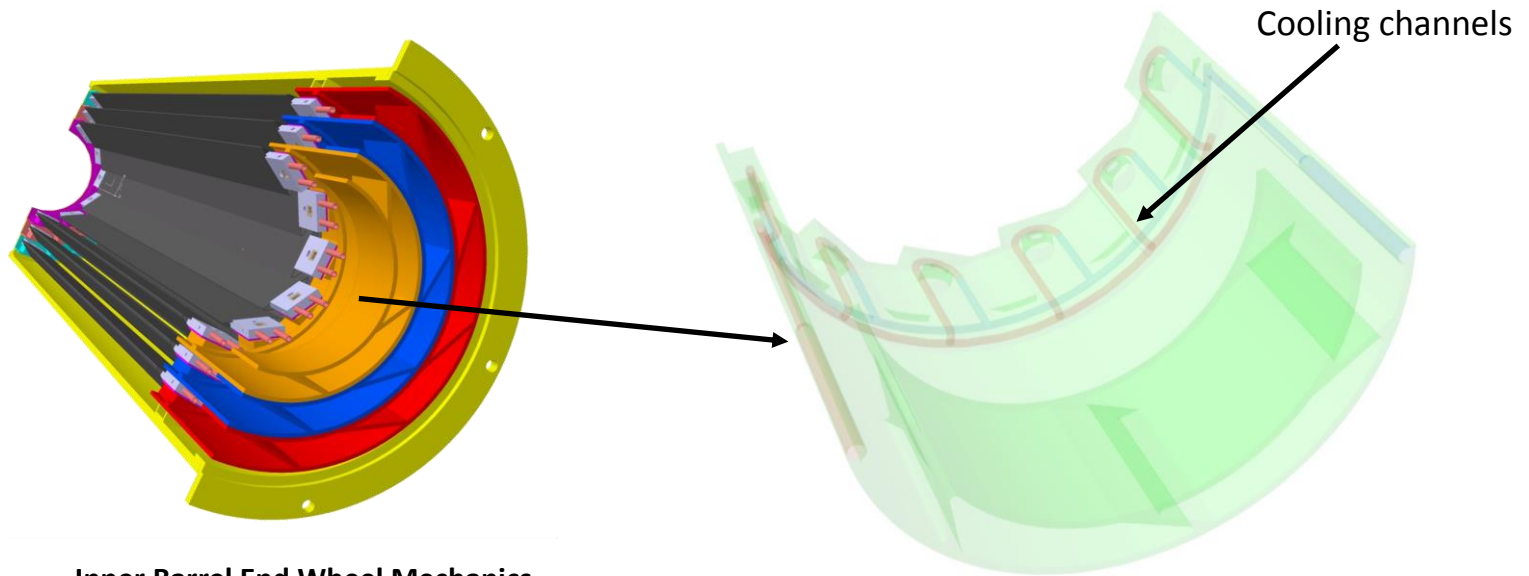
Carbon fibre support structure and integrated cooling plate with cooling channels

# Example: ALICE ITS Outer Barrel Stave



# ALICE ITS Upgrade

**Additive manufacturing techniques** used for rapid prototyping and for building parts of the mechanics and cooling of the ITS Upgrade:



Inner Barrel End Wheel Mechanics  
including cooling channels being produced in Accura Bluestone (3D printing)  
C. Gargiulo/PH-DT

# Conclusions

- \* Very satisfactory use of additive manufacturing technologies to support particle detector R&D and assembly (even with a 40k printer!)
- \* Advantages demonstrated... by the book: creation of impossible shapes, visualization, fast turnaround, cost reduction, democratized manufacturing (students!), etc
- \* Further development passes by
  - \* Using materials that are standard in HEP (carbon, silicon, kapton... ) i.e. radhard, light, outgassing-free, thermomechanically suitable, non-magnetic...
  - \* Using multi-materials to print detectors and services (power, readout, cooling) at once
  - \* Combining design, manufacturing and QA in one machine